PCN Number:	20230412	20230412001.1					ate:	April 12, 2023	
Title: Qualification of a new die attach material for select devices									
Customer Cont	act: PCN A	<u>Nanager</u>	Dept:	Quality Servio	es				
Proposed 1 <sup>st</sup> Ship Date: Jul 11,			2023 Sample I		-	Ad until: May 12, 2023			
*Sample reque	sts receive	d after	May 12, 2						
Change Type:									
Assembly Site			Design			Wafer Bump Site			
Assembly Pr			Data Sheet				Wafer Bump Material		
Assembly M				☐ Part number change ☐ Test Site			Wafer Bump Process Wafer Fab Site		
<ul> <li>Mechanical Specification</li> <li>Packing/Shipping/Labeling</li> </ul>			Test Process			_		Materials	
							Wafer Fab Process		
			PCN	Details					
Description of Change:									
This PCN is to inform of an alternate die attach material for the devices listed below.									
,	What			Current		New			
Die atta	ach materia	1		4208458		4211470			
Reason for Cha	nge:								
Continuity of supply									
Anticipated imp	pact on For	m, Fit,	Function,	Quality or Re	lia bilit	y (posit	ive / I	negative):	
None									
Impact on Envi	ronmental	Rating	S						
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.									
RoHS R		EACH Green Statu			s	IEC	C 62474		
🛛 No Change 🛛 🖾 No Ch		ange 🛛 🛛 No Change			$\square$	🛛 No Change			
Changes to product identification resulting from this PCN:									
None									
Product Affected:									
	/10987SLIPWPR LM5176PWP			TAS5806MDCPF			TPA3113D2PWPR		
DRV8818PWP				TAS5806MDDC			TPA3118D2DAP		
DRV8818PWPR	SN005805PWI			TAS5806MDDC			TPA3118D2DAPR		
	DRV8840PWP SN8C0183PW					TPA3130D2DAP			
DRV8840PWPR		C0183PW				TPA3130D2DAPR			
-	DRV8876NPWPR SNB9039DCP					TPA3138D2PWP			
DRV8876NPWPT		5805M0P				TPA3138D2PWPR			
DRV8876PWPR	TAS5805MPWP		VP	TPA3110D2PWPR		TPS8802DCPR			

DRV8876PWPT TAS5805MPWPR TPA3113D2PWP
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TI Information Selective Disclosure

## **Qualification Report**

#### Approve Date 07-APRIL -2023

## **Qualification Results**

#### Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>TAS5807MDCPR</u>	Qual Device: <u>TLS2605RDCARG4</u>	QBS Reference: LP8880DCPRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0	3/231/0
тс	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0

• QBS: Qual By Similarity

• Qual Device TAS5807MDCPR and TLS2605RDCARG4 are qualified at MSL3 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2207-055

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN ww admin team@list.ti.com

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